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1. JP2001131509A 20010515 NON-HALOGENATED RESIN COMPOSITION FOR ADHESIVE TAPE, FILM WHICH IS FORMED FROM THE SAME AND IS USED FOR ADHESIVE TAPE, AND ADHESIVE TAPE

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PROBLEM TO BE SOLVED: To provide a non- halogenated resin composition for an adhesive tape in which a plasticizer contained in a film is transferred to an adhesive layer to ensure tackiness and adhesiveness the same as or higher than those of conventional polyvinyl halide adhesive tapes, to provide a film which is formed from the same and is useful for an adhesive tape, and to provide the adhesive tape.

SOLUTION: This non-halogenated resin composition for adhesive tape, comprising 100 pts.wt. of a polyolefin-based resin and 60 to 150 pts.wt. of an inorganic flame retardant, characterized by containing 3 to 5 pts. wt. of a plasticizer. The polyolefin-based resin is preferably at least one resin selected from polyethylene, polypropylene, ethylene-ethyl acrylate copolymer, ethylene-methyl acrylate copolymer, ethylene-vinyl acetate copolymer, ethylene-propylene copolymer, ethylene-hexene copolymer and ethylene-octene copolymer. The plasticizer is preferably at least one compound selected from dioctyl phthalate, diisononyl phthalate, diisodecyl phthalate and ditiisodecyl phthalate.

Legal Status: There is no Legal Status information available for this patent
